

IEEE跨国电气电子工程师协会第14届国际固态和集成电路技术会议(ICSICT)



目的地：青岛

参加人数：600人

服务内容：会议管理、交通统筹、展位搭建、活动执行、注册报名系统

成功亮点：学术会议致力于搭建学术交流的平台，参会专家因此成为学术会议的核心资源之一。本次大会会有150余位国内外专家，世界各地的高校科研工作者、学术带头人和相关企业来宾，其中外籍专家近百名。共64场会议、473个讲座/报告使专家行程安排变得更具挑战。桂林康辉项目团队专业的服务保障了嘉宾有条不紊的参加本届ICSICT各个环节。



Qingdao, China

Section

北京大学
PEKING UNIVERSITY

山东省教育厅
Shandong Provincial Education Department

西海岸新区
West Coast New Area



PDA
DESIGN AUTOMATION, INC.

PROPLUS
THE PROPLUS GROUP

Sponsored by

Cosponsored by

ICSICT 大会副主席 Ting-Ao Tang 致欢迎词



Industry Trends in ESD

- ESD protection compliance has become a bottleneck in the semiconductor industry
- Designing effective on-chip ESD protection solutions for the sub-22nm CMOS technology has been very challenging
- TSMC, Samsung, and Intel are foundries that can currently offer the sub-16nm FinFET nodes, but the lack of robust ESD protection solutions is a main roadblock for this technology and beyond.
- Off-chip ESD protection solutions, which can be realized in a mature process technology, are being considered as a viable option to enhance the system-level ESD robustness.
- Gate- and system-level ESD protection solutions will be increasingly sought after in the coming years.
- Chip-level and system-level compact models for ESD event simulations is a new industry focus.
- ESD/EMI (electromagnetic interference) co-design is a new reliability requirement for future integrated circuits.

ICSICT 分会场一隅

ICSICT 主会场 青岛喜来登酒店



ICSICT 2018 活动颁奖晚宴